

MOSFET – N-Channel, POWER TRENCH[®], SyncFET[™]

30 V, 49 A, 2.8 mΩ

FDMS0308AS, FDMS0308AS-NC

General Description

The FDMS0308AS has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest $R_{DS(on)}$ while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic Schottky body diode.

Features

- Max $R_{DS(on)}$ = 2.8 mΩ at V_{GS} = 10 V, I_D = 24 A
- Max $R_{DS(on)}$ = 3.5 mΩ at V_{GS} = 4.5 V, I_D = 21 A
- Advanced Package and Silicon Combination for Low $R_{DS(on)}$ and High Efficiency
- SyncFET Schottky Body Diode
- MSL1 Robust Package Design
- 100% UIL Tested
- RoHS Compliant

Applications

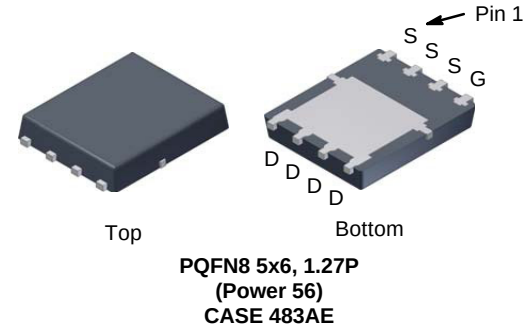
- Synchronous Rectifier for DC-DC Converters
- Notebook Vcore/GPU Low Side Switch
- Networking Point of Load Low Side Switch
- Telecom Secondary Side Rectification

MOSFET MAXIMUM RATINGS (T_C = 25 °C unless otherwise noted)

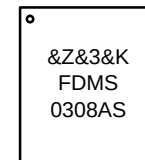
Symbol	Parameter	Ratings	Unit
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	±20	V
I_D	Drain Current: – Continuous (Package Limited) T_C = 25 °C – Continuous (Silicon Limited) T_C = 25 °C – Continuous T_A = 25 °C (Note 1a) – Pulsed	49 109 24 100	A
E_{AS}	Single Pulse Avalanche Energy (Note 3)	66	mJ
P_D	Power Dissipation T_C = 25 °C T_A = 25 °C (Note 1a)	50 2.5	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

V_{DS}	$R_{DS(on)}$ MAX	I_D MAX
30 V	2.8 mΩ @ 10 V	49 A
	3.5 mΩ @ 4.5 V	

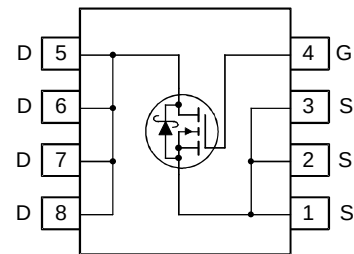


MARKING DIAGRAM



&Z = Assembly Plant Code
&3 = 3-Digit Date Code Format
&K = 2-Digits Lot Run Traceability Code
FDMS0308AS = Specific Device Code

PIN ASSIGNMENT



ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 10\text{ mA}$, referenced to $25\text{ }^{\circ}\text{C}$		19		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}$, $V_{GS} = 0\text{ V}$			500	μA
I_{GSS}	Gate to Source Leakage Current, Forward	$V_{GS} = 20\text{ V}$, $V_{DS} = 0\text{ V}$			100	nA

ON CHARACTERISTICS

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 1\text{ mA}$	1.2	1.7	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 10\text{ mA}$, referenced to $25\text{ }^{\circ}\text{C}$		-5		mV/°C
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$, $I_D = 24\text{ A}$		2.2	2.8	mΩ
		$V_{GS} = 4.5\text{ V}$, $I_D = 21\text{ A}$		3.0	3.5	
		$V_{GS} = 10\text{ V}$, $I_D = 24\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$		3.1	4.0	
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{ V}$, $I_D = 24\text{ A}$		145		S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = 15\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$		2255	3000	pF
C_{oss}	Output Capacitance			815	1085	pF
C_{rss}	Reverse Transfer Capacitance			85	125	pF
R_g	Gate Resistance			1.0	2.5	Ω

SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}$, $I_D = 24\text{ A}$, $V_{GS} = 10\text{ V}$, $R_{GEN} = 6\text{ }^{\circ}\Omega$		11	19	ns
t_r	Rise Time			4.5	10	ns
$t_{d(off)}$	Turn-Off Delay Time			29	46	ns
t_f	Fall Time			3.7	10	ns
Q_g	Total Gate Charge	$V_{GS} = 0\text{ V}$ to 10 V , $V_{DD} = 15\text{ V}$, $I_D = 24\text{ A}$		34	47	nC
Q_g	Total Gate Charge	$V_{GS} = 0\text{ V}$ to 4.5 V , $V_{DD} = 15\text{ V}$, $I_D = 24\text{ A}$		16	23	nC
Q_{gs}	Gate to Source Charge	$V_{DD} = 15\text{ V}$, $I_D = 24\text{ A}$		5.9		nC
Q_{gd}	Gate to Drain "Miller" Charge			4.6		nC

DRAIN-SOURCE DIODE CHARACTERISTICS

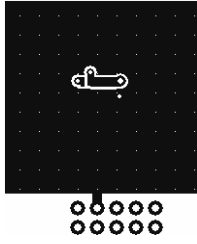
V_{SD}	Source-Drain Diode Forward Voltage	$V_{GS} = 0\text{ V}$, $I_S = 2\text{ A}$ (Note 2)		0.62	0.8	V
		$V_{GS} = 0\text{ V}$, $I_S = 24\text{ A}$ (Note 2)		0.8	1.2	
t_{rr}	Reverse Recovery Time	$I_F = 24\text{ A}$, $di/dt = 300\text{ A}/\mu\text{s}$		26	42	ns
Q_{rr}	Reverse Recovery Charge			27	44	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

FDMS0308AS, FDMS0308AS-NC

NOTES:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.
3. E_{AS} 66 mJ is based on starting $T_J = 25$ °C, $L = 0.3$ mH, $I_{AS} = 21$ A, $V_{DD} = 27$ V, $V_{GS} = 10$ V.
4. As an N-ch device, the negative V_{GS} rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

TYPICAL CHARACTERISTICS ($T_J = 25$ °C unless otherwise noted)

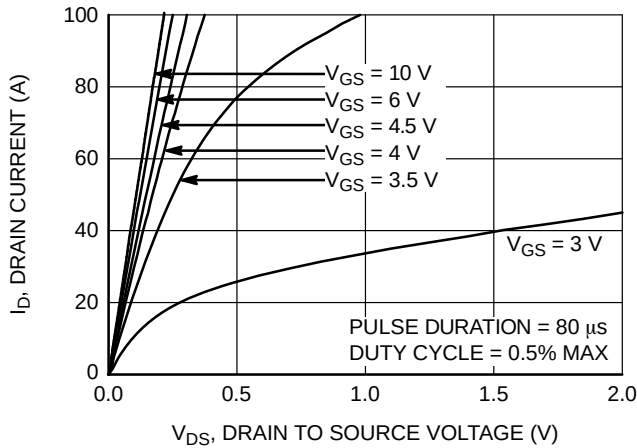


Figure 1. On Region Characteristics

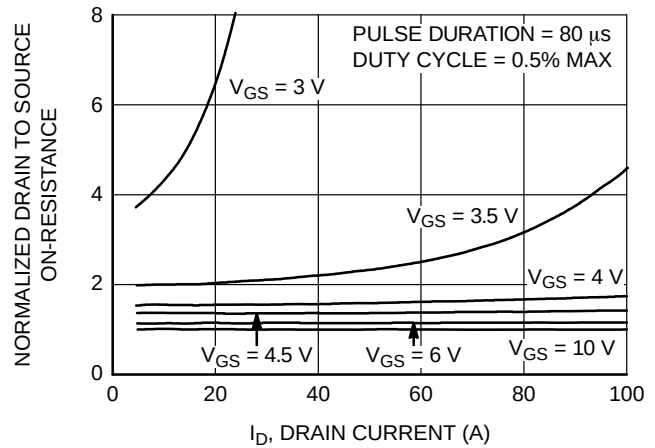


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

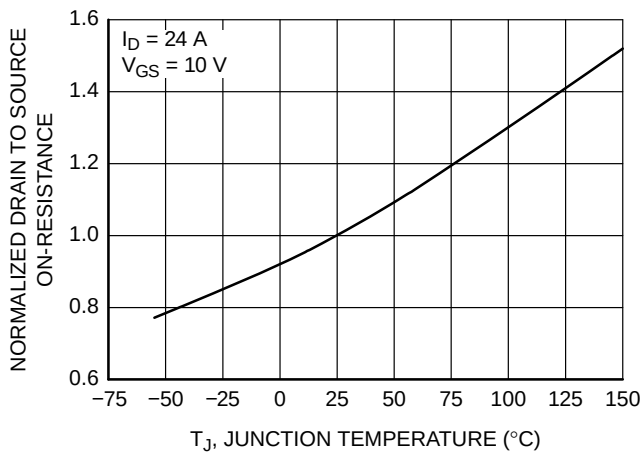


Figure 3. Normalized On-Resistance vs. Junction Temperature

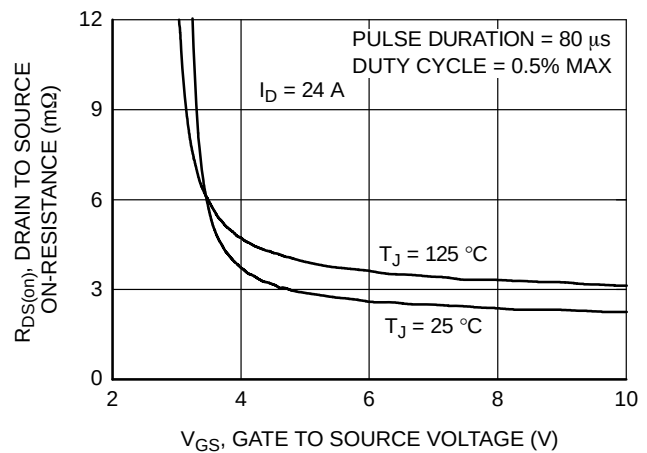


Figure 4. On-Resistance vs. Gate to Source Voltage

TYPICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted) (continued)

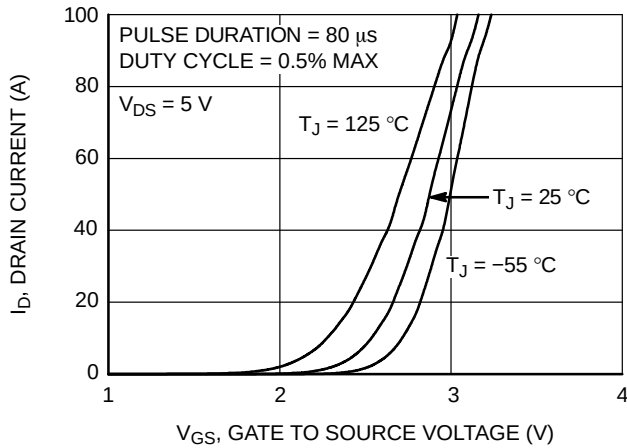


Figure 5. Transfer Characteristics

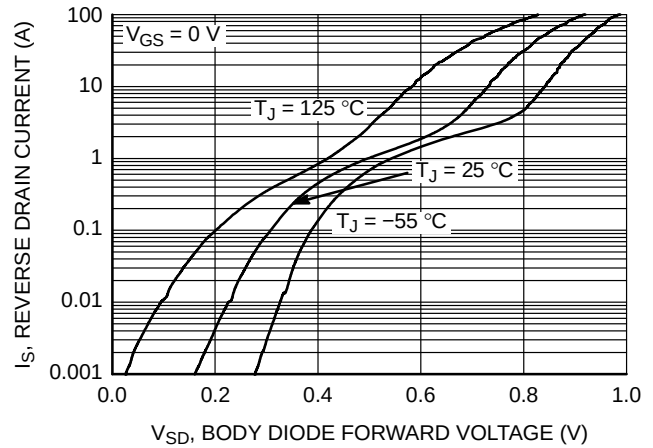


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

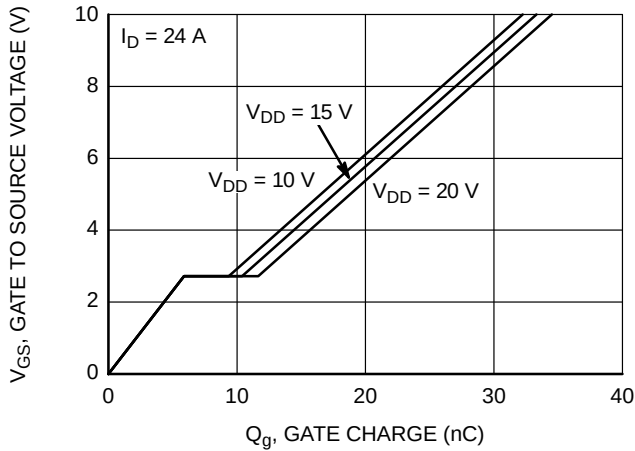


Figure 7. Gate Charge Characteristics

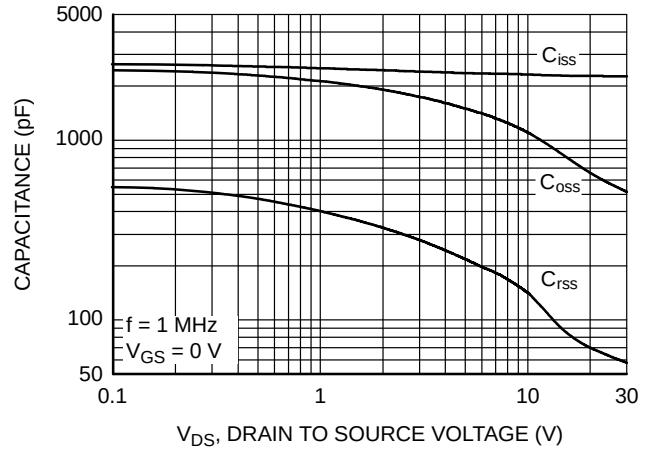


Figure 8. Capacitance vs. Drain to Source Voltage

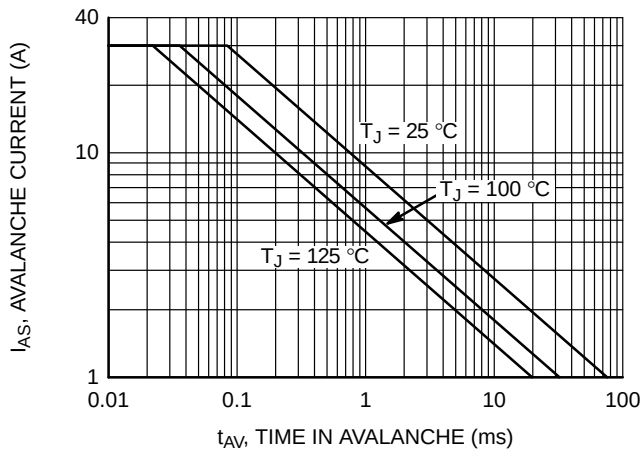


Figure 9. Unclamped Inductive Switching Capability

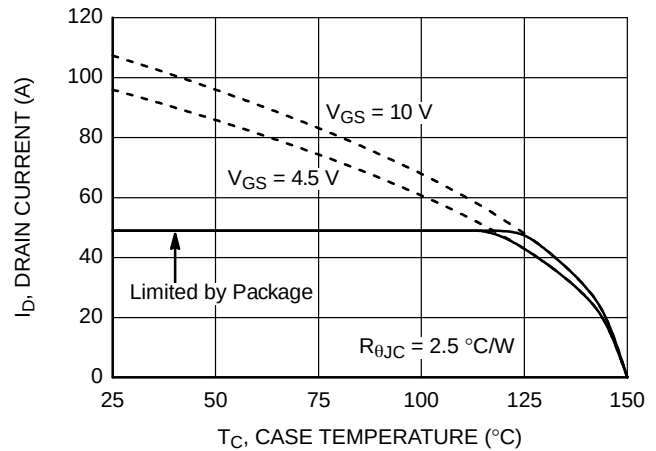


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

TYPICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise noted) (continued)

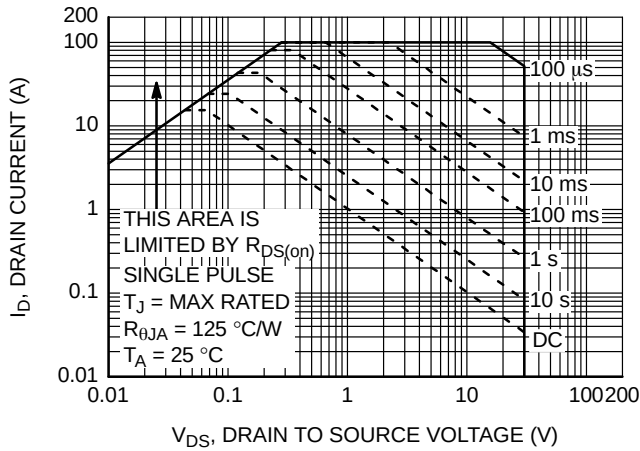


Figure 11. Forward Bias Safe Operating Area

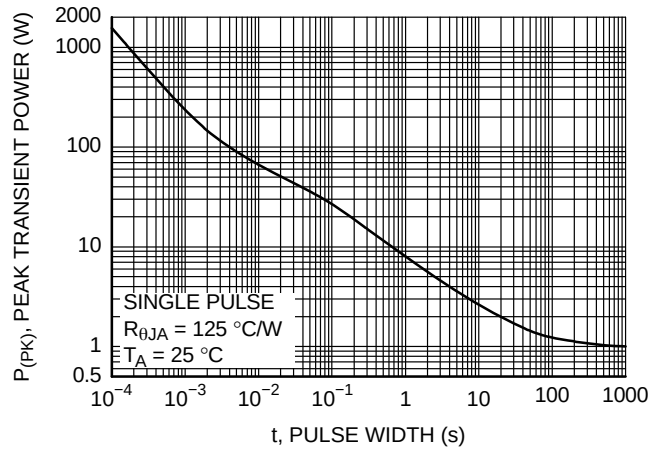


Figure 12. Single Pulse Maximum Power Dissipation

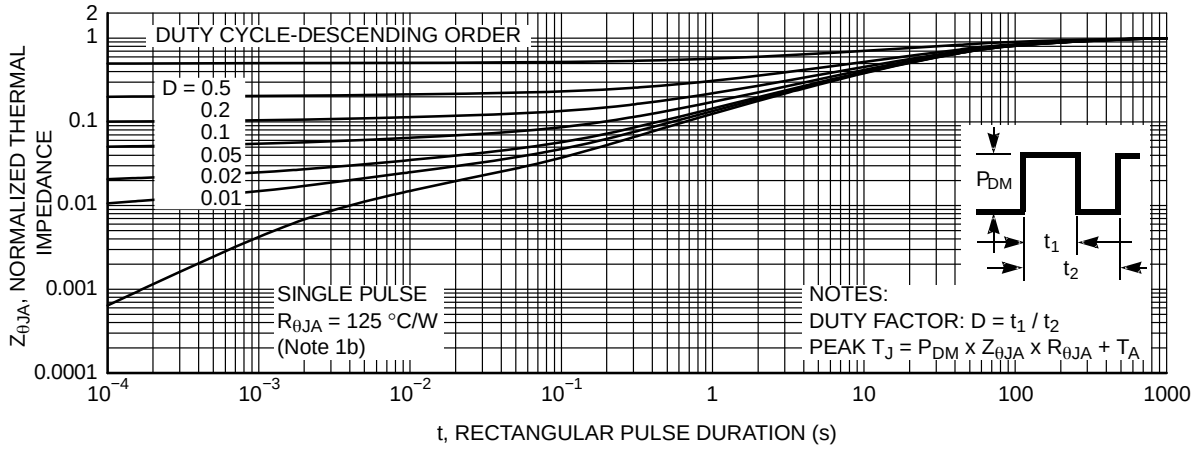


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

TYPICAL CHARACTERISTICS (continued)

SyncFET Schottky Body Diode Characteristics

onsemi's SyncFET process embeds a Schottky diode in parallel with POWERTRENCH MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverse recovery characteristic of the FDMS0308AS.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

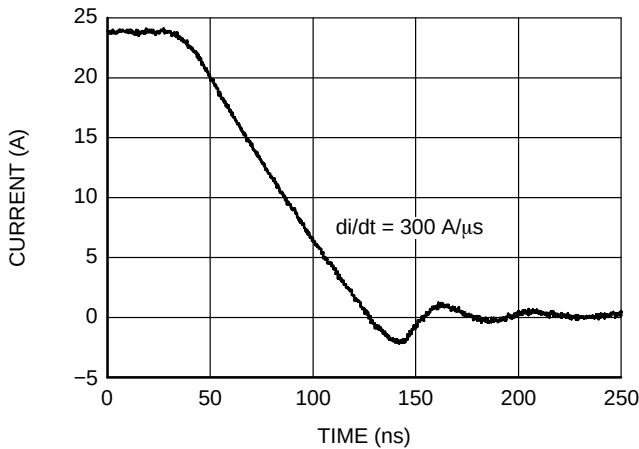


Figure 14. FDMS0308AS SyncFET Body Diode Reverse Recovery Characteristic

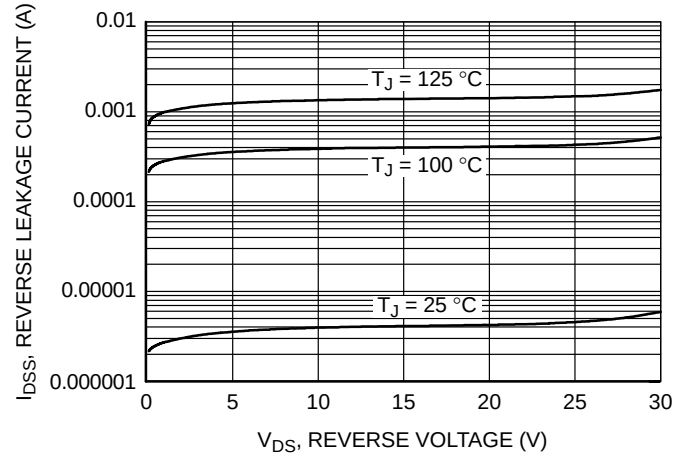


Figure 15. SyncFET Body Diode Reverse Leakage vs. Drain-Source Voltage

PACKAGE MARKING AND ORDERING INFORMATION

Device	Device Marking	Package	Reel Size	Tape Width	Shipping [†]
FDMS0308AS	FDMS0308AS	PQFN8 5x6, 1.27P (Power 56)	13"	12 mm	3000 / Tape & Reel
FDMS0308AS-NC					

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

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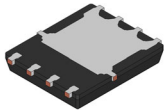
FDMS0308AS, FDMS0308AS-NC

REVISION HISTORY

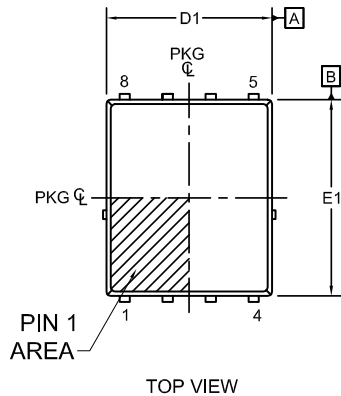
Revision	Description of Changes	Date
2	Document converted to onsemi format. Added FDMS0308AS-NC device.	9/8/2026

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

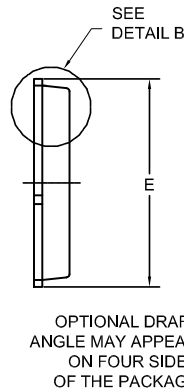



PQFN8 5X6, 1.27P
CASE 483AE
ISSUE C

DATE 21 JAN 2022

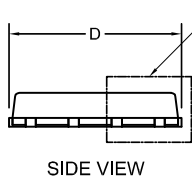


TOP VIEW

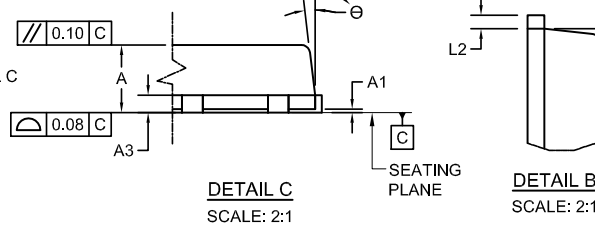
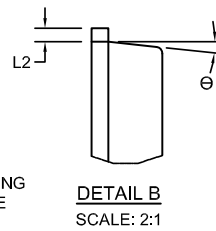
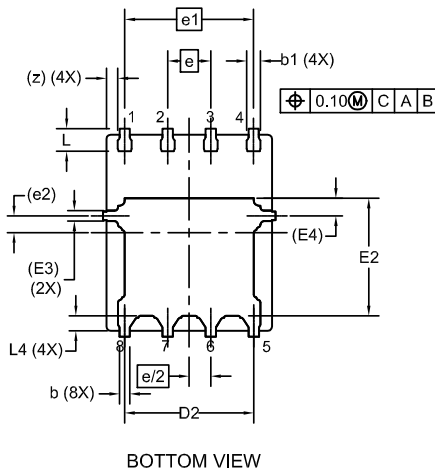


NOTES:

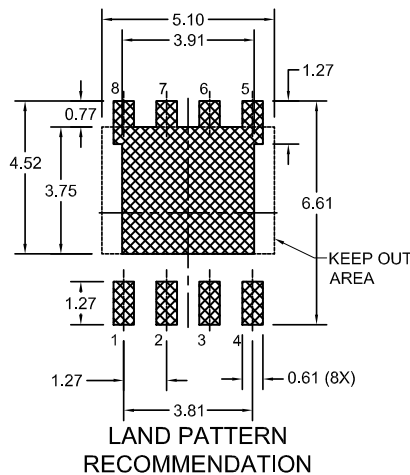
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
6. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



SIDE VIEW


DETAIL C
SCALE: 2:1

DETAIL B
SCALE: 2:1


BOTTOM VIEW


LAND PATTERN
RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	-	0.05
b	0.21	0.31	0.41
b1	0.31	0.41	0.51
A3	0.15	0.25	0.35
D	4.90	5.00	5.20
D1	4.80	4.90	5.00
D2	3.61	3.82	3.96
E	5.90	6.15	6.25
E1	5.70	5.80	5.90
E2	3.38	3.48	3.78
E3	0.30 REF		
E4	0.52 REF		
e	1.27 BSC		
e/2	0.635 BSC		
e1	3.81 BSC		
e2	0.50 REF		
L	0.51	0.66	0.76
L2	0.05	0.18	0.30
L4	0.34	0.44	0.54
z	0.34 REF		
Θ	0°	-	12°

DOCUMENT NUMBER: 98AON13655G

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DESCRIPTION: PQFN8 5X6, 1.27P

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